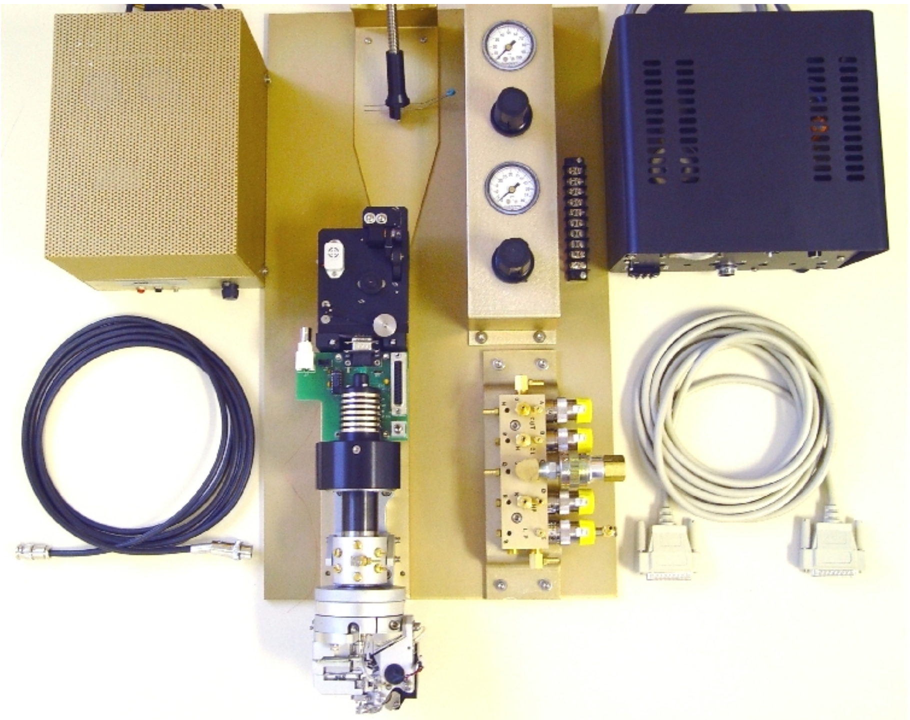
PCKTECHNOLOGYINC

Wire Embedding Subsystem

PCK's wire embedding subsystem is the ideal choice for system integrators, offering an affordable automation solution. One or more head modules can be integrated into custom bases using the desired motion platform.

The subsystem consists of the wire embedding head and associated electronic circuitry, the ultrasonic generator, the power supply and the regulators. Ultrasonic power modulation is the key to efficiently melting the thermoplastic and other substrate materials and to activate the adhesive coated self bonding wire. The wire is pressed into the melted thermoplastic substrate to form a true mechanical bond between the wire and the substrate.

PCK has been providing wire embedding technology and equipment to high performance electronic circuit manufacturers for over 30 years and services a licensed manufacturing base worldwide.



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